



Irish Standard  
I.S. EN 61182-2-2:2012

Printed board assembly products -  
Manufacturing description data and  
transfer methodology -- Part 2-2:  
Sectional requirements for  
implementation of printed board  
fabrication data description (IEC 61182  
-2-2:2012 (EQV))

## I.S. EN 61182-2-2:2012

*Incorporating amendments/corrigenda issued since publication:*

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**EN 61182-2-2**

June 2012

ICS 31.180

English version

**Printed board assembly products -  
Manufacturing description data and transfer methodology -  
Part 2-2: Sectional requirements for implementation  
of printed board fabrication data description  
(IEC 61182-2-2:2012)**

Produits pour cartes imprimées équipées -  
Données descriptives de fabrication  
et méthodologie de transfert -  
Partie 2-2: Exigences intermédiaires pour  
la mise en oeuvre de cartes imprimées -  
Description des données de fabrication  
(CEI 61182-2-2:2012)

Leiterplatten -  
Beschreibung und Transfer von Daten -  
Teil 2-2: Anforderungen für die  
Anwendung von Dokumentationsdaten  
der Leiterplattenfertigung  
(IEC 61182-2-2:2012)

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Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Management Centre: Avenue Marnix 17, B - 1000 Brussels**

## **Foreword**

The text of document 91/1025/FDIS, future edition 1 of IEC 61182-2-2, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61182-2-2:2012.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2013-03-01
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2015-06-01

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61188-5-1	NOTE	Harmonised as EN 61188-5-1.
IEC 61188-5-2	NOTE	Harmonised as EN 61188-5-2.
IEC 61188-5-3	NOTE	Harmonised as EN 61188-5-3.
IEC 61188-5-4	NOTE	Harmonised as EN 61188-5-4.
IEC 61188-5-5	NOTE	Harmonised as EN 61188-5-5.
IEC 61188-5-6	NOTE	Harmonised as EN 61188-5-6.
IEC 61188-5-8	NOTE	Harmonised as EN 61188-5-8.
ISO 10303-210	NOTE	Harmonised as EN ISO 10303-210.

**Annex ZA**  
(normative)**Normative references to international publications  
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 61182-2	-	Printed board assembly products - Manufacturing description data and transfer methodology - Part 2: Generic requirements	-	-

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## CONTENTS

FOREWORD.....	4
1 Scope.....	6
2 Normative references .....	6
3 Terms and definitions .....	6
4 General principles .....	7
4.1 Requirements .....	7
4.2 Interpretation.....	7
4.3 Categories and content .....	8
5 General rules.....	9
5.1 Overview .....	9
5.2 File content descriptions.....	10
5.3 Logistic descriptions.....	10
5.4 File history descriptions.....	10
5.4.1 General .....	10
5.4.2 HistoryRecord use case – Initial design release.....	11
5.4.3 Supply chain modifications .....	12
5.4.4 OEM reviews modifications – HistoryRecord update .....	14
5.5 BOM (board fabrication materials).....	14
5.6 AVL (board material suppliers) .....	16
5.7 Documentation layers.....	16
5.7.1 General .....	16
5.7.2 Documentation layer restrictions.....	16
5.7.3 Reference to documentation .....	17
5.7.4 Step usage .....	18
5.7.5 Set .....	19
5.8 Design for excellence (Dfx) analysis.....	19
5.8.1 General .....	19
5.8.2 DfxMeasurement .....	19
5.9 Miscellaneous image layers.....	19
5.9.1 General .....	19
5.9.2 Step usage .....	20
5.10 Packages and land patterns .....	20
5.10.1 General .....	20
5.10.2 Step usage for component packages and land patterns .....	20
5.10.3 Land pattern details.....	21
5.11 Solder mask and legend layers.....	21
5.11.1 General .....	21
5.11.2 Solder mask details .....	21
5.11.3 Legend details.....	21
5.11.4 Step usage for solder mask and legend layers.....	22
5.12 Drilling and routing (tooling) layers.....	22
5.12.1 General .....	22
5.12.2 Drilling details.....	22
5.12.3 Routing details .....	22
5.12.4 Step usage for drilling and routing .....	23
5.13 Net list.....	23

**I.S. EN 61182-2-2:2012**

61182-2-2 © IEC:2012

– 3 –

5.13.1	General .....	23
5.13.2	Step usage for net list.....	24
5.14	Outer conductive layers .....	24
5.14.1	General .....	24
5.14.2	Outer conductive layer details .....	24
5.14.3	Step usage for outer conductive layers .....	24
5.15	Inner conductive layers .....	25
5.15.1	Requirement.....	25
5.15.2	Inner conductive layer details .....	25
5.15.3	Step usage for inner conductive layers .....	25
5.16	Board construction .....	25
5.16.1	Requirement.....	25
5.16.2	Board construction details .....	26
5.16.3	Step usage for board construction .....	26
6	Modeling .....	26
6.1	General.....	26
6.2	Information models.....	27
7	Report generators .....	28
7.1	IEC 61182-2-2 format.....	28
7.2	Hole usage report.....	29
7.3	Pad usage report.....	29
7.4	Conductor usage report.....	29
8	Glossary.....	29
	Annex A (normative) Printed board fabrication schema .....	30
	Bibliography.....	42
	Figure 1 – Board fabrication data relationship .....	9
	Figure 2 – HistoryRecord use case .....	11
	Figure 3 – Documentation package grade requirements.....	18
	Figure 4 – Fabrication steps data model example .....	27
	Figure 5 – IPC-2584 UML data model .....	28
	Table 1 – Function relationship of an IEC 61182-2-2 fabrication file .....	8
	Table 2 – Bom restrictions .....	15
	Table 3 – Recommended reference designators for printed board material .....	15
	Table 4 – Avl restrictions .....	16
	Table 5 – Documentation layer restrictions .....	17
	Table 6 – General descriptions of documentation layer functions .....	17
	Table 7 – Relationship to documentation standard .....	18
	Table 8 – Miscellaneous layer restrictions.....	20



## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**PRINTED BOARD ASSEMBLY PRODUCTS –  
MANUFACTURING DESCRIPTION DATA  
AND TRANSFER METHODOLOGY –**
**Part 2-2: Sectional requirements for implementation  
of printed board fabrication data description**
**FOREWORD**

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International Standard IEC 61182-2-2 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1025/FDIS	91/1038/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

**I.S. EN 61182-2-2:2012**

61182-2-2 © IEC:2012

– 5 –

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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## **PRINTED BOARD ASSEMBLY PRODUCTS – MANUFACTURING DESCRIPTION DATA AND TRANSFER METHODOLOGY –**

### **Part 2-2: Sectional requirements for implementation of printed board fabrication data description**

#### **1 Scope**

This part of IEC 61182 provides the information on the manufacturing requirements used for fabricating printed boards. This standard determines the XML schema details, defined in the generic standard IEC 61182-2 and some of the sectional standards that are required to accomplish the focused tasks. When other standards are invoked, their requirements become a mandatory part of the fabrication details as defined in the IEC 61182-2.

The IEC 61182-2 contains all the requirements necessary to build an electronic product. The cardinality indicated in the IEC 61182-2 may be superseded by a restriction of an attribute (enumerated string ID) or indication of a requirement that is noted as being optional in the generic standard. However, this standard renders the requirement mandatory based on the supply chain communication need.

In order to assist the users of this standard, all the applicable XML schema elements that apply to the board fabrication function are listed in Annex A. The list is grouped by topics and shows the absolute path for the elements that pertain to the focus of this standard. If the parent element is not present no children are considered in the implementation either. However, all attributes identified for a particular element follow the cardinality of the IEC 61182-2, unless a restriction is stated in this standard.

#### **2 Normative references**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61182-2, *Printed board assembly products – Manufacturing description data and transfer methodology – Part 2: Generic requirements*

#### **3 Terms and definitions**

For the purposes of this document, the terms and definitions of IEC 60194 as well as the following apply.

##### **3.1 data**

intelligent information that may be used directly by machine in order to accomplish a particular manufacturing event

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